

FEATURES

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Stable,High temperature,Glass passivated junction
- -V suffix for Automative and other applications requiring unique site and control change requirments
- PPAP capable
- AEC-Q101 qualified
- High temperature soldering guaranteed:260°C/10 seconds at terminals
- Component in accordance to RoHS 2015/863/EU



AEC-Q101 Qualified

MECHANICAL DATA

- Case: SMAF molded plastic body
- Terminals: Solder Plated, solderable per MIL-STD-750,method 2026
- Polarity: Color band denotes cathode end

SMAF



TYPICAL APPLICATIONS

For use in high voltage rectifier,polarity protection,clamp applications

MAXIMUM RATINGS

(Ratings at 25°C ambient temperature unless otherwise specified)

Parameters	Symbol	Value	Unit
Maximum repetitive peak reverse voltage	V_{RRM}	1000	V
Maximum average forward rectified current	$I_{F(AV)}$	1.0	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC method at rated TL)	I_{FSM}	30	A
Operating junction temperature range	T_J	-55 to+150	°C
Storage temperature range	T_{stg}	-55 to+150	°C

ELECTRICAL CHARACTERISTICS (T_A=25°C Unless otherwise noted)

Parameter	Test Conditions		Symbol	Min.	Typ.	Max.	Unit
Breakdown voltage Blocking voltage	I _R =10μA	T _J =25°C	V _{BR} V _R	1150	-	-	V
		T _J =-55°C		1000	-	-	
Instaneous forward voltage	I _F =1.0A	T _J =-40°C	V _F ¹⁾	-	-	1.20	V
		T _J =25°C		-	0.95	1.00	
		T _J =125°C		-	0.85	-	
Reverse current	V _R =1000V	T _J =25°C	I _R ²⁾	-	-	2	μA
		T _J =100°C		-	-	50	
		T _J =125°C		-	-	250	
Junction capacitance	4V, 1MHz		C _J	-	6.0	-	pF

Notes: 1.Pulse test: 300μs pulse width,1% duty cycle

2.Pulse test: pulse width ≤40ms

THERMAL CHARACTERISTICS

Parameter	Symbol	SMAF	Unit
Typical thermal resistance	R _{θJA} ^{3) 4)}	150	°C/W
	R _{θJM}	15	

3.The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_c/dT_j < 1/R_{\theta JA}$

4.Thermal resistance junction-to-ambient to follow JEDEC51-2A, device mounted on FR4 PCB, 2 oz., standard footprint

5.Thermal resistance junction-to-mount to follow JEDEC51-14 transient dual interface test method (TDIM)

AVAILABLE PACK INFORMATION

Product code	Pack	Reel Size (mm)	Quantity (pcs/reel)	Box Size L×W×H (mm)	Quantity (reel/box)	Carton Size L×W×H (mm)	Quantity (box/carton)
S1MS-V-SMAF	T/R	Φ178	3000	180×73×180	2	380×380×200	10

FIG.1-FORWARD CURRENT DERATING CURVE

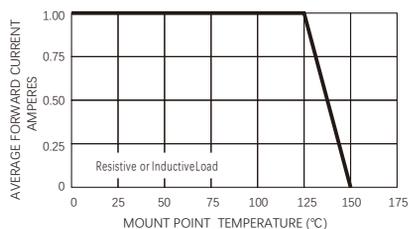


FIG.2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

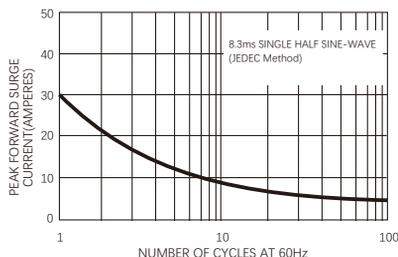


FIG.3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

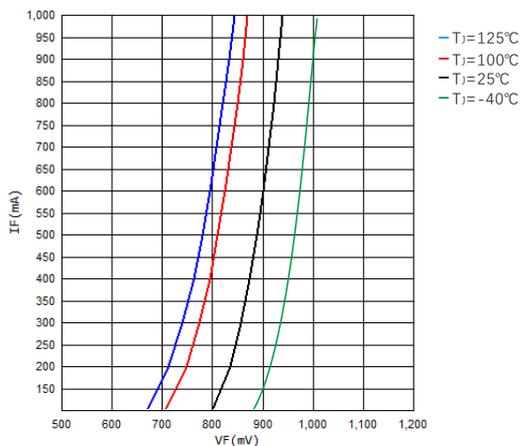


FIG.4-TYPICAL REVERSE CHARACTERISTICS

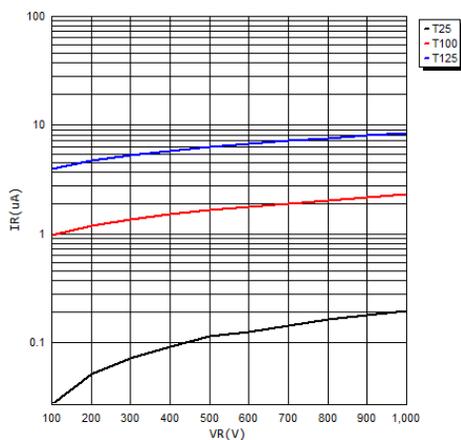
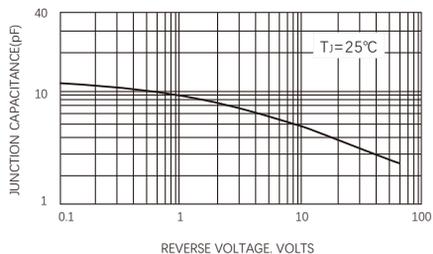
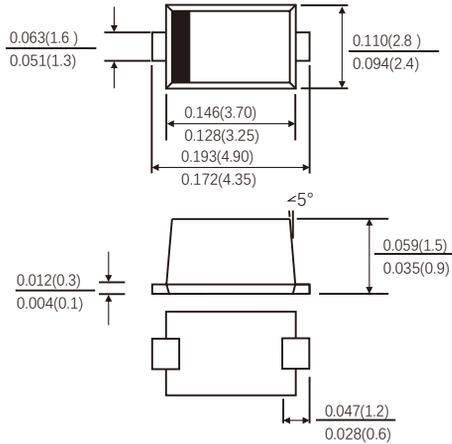


FIG.5-TYPICAL JUNCTION CAPACITANCE



SMAF



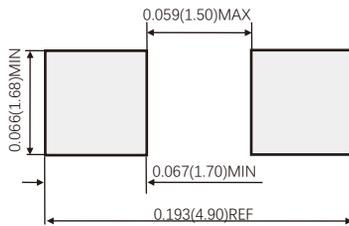
Marking



Marking:

JF:Logo
 xxx:Tracing code
 S1MS-V: Type

Suggested PAD Layout



Dimensions in inches and (millimeters)

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